



**L&L BOND HEAT-ACTIVATED
STRUCTURAL ADHESIVES**

**Lightweight, High-
Performance Engineered
Solutions for Bonding.**

L&L Bond Structural Adhesive Tapes are high-performance, heat-activated structural adhesives that are applied prior to the E-coat bake process. The materials foam (in some cases) and cure in the E-coat oven to provide structural bonding.

lproducts.com

L&L BOND HEAT-ACTIVATED STRUCTURAL ADHESIVES

Alternative to Costly Welding Operations.

Tacky in the uncured state, these heat-activated adhesives are ideal for use where access is limited for welding or mechanical fastening. The material includes a permanent film on the top surface for easy handling. This permanent film transforms into an adhesive with heat activation.

When bonding dissimilar substrates, the tapes resist stresses created by coefficient of thermal expansion differences while preventing galvanic corrosion as a nonconductive adhesive spacer.



Tapes are applied prior to the E-coat oven.

KEY PRODUCT ATTRIBUTES



SUPERIOR ADHESION

- Superior initial (uncured) adhesion to a wide range of substrates
- High peel strength



DESIGN FLEXIBILITY

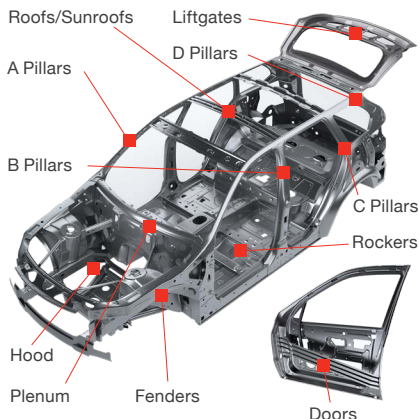
- Bonds dissimilar metals
- High expansion
- Ductile & pliable prior to curing for contoured surfaces



PROCESS OPTIMIZATION

- Solid, dry-to-touch with permanent film on top
- Pressure sensitive
- Alternative to welding and mechanical fasteners

APPLICATIONS



CUSTOM ENGINEERED SOLUTIONS



STRUCTURAL PRESSURE SENSITIVE ADHESIVES

These heat-activated tapes allow manufacturers to bond areas where there are minimal gaps, limited weld accessibility, and dissimilar substrate materials.



GAP-JUMPING PRESSURE SENSITIVE ADHESIVES

Our heat-activated gap-jumping Pressure Sensitive Adhesives **foam up to 275% to bridge varying gaps.**

